Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (1.7 EP)
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS012587A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.02E-03	84.50	845000	34.57	345684
Thermosets	Epoxy & Phenol Resin	Proprietary	1.25E-03	15.00	150000	6.14	61364
Other inorganic materials	Carbon black	1333-86-4	4.15E-05	0.50	5000	0.20	2045
Subtotal			8.30E-03	100.00	1000000	40.91	409094

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.61 E-03	96.40	963989	47.32	473234
Copper & its alloys	Iron	7439-89-6	2.49 E-04	2.50	25006	1.23	12276
Copper & its alloys	Zinc	7440-66-6	5.98 E-05	0.60	6004	0.29	2947
Copper & its alloys	Phosphorus	7723-14-0	4.98 E-05	0.50	5001	0.25	2455
Subtotal			9.97 E-03	100.00	1000000	49.09	490912

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.49 E-05	100.0	1000000	0.12	1227

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.75 E-04	100.0	1000000	2.34	23377

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.70 E-05	99.00	990000	0.23	2314
Precious metals	Palladium	7440-05-3	4.75 E-07	1.00	10000	0.002	23
Subtotal			4.75 E-05	100.0	1000000	0.23	2338

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.42 E-03	100.0	1000000	7.01	70130

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.57 E-05	77.00	770000	0.23	2250
Other organic materials	Acrylic resin	Proprietary	4.15 E-06	7.00	70000	0.02	205
Other organic materials	Acrylate	Proprietary	3.26 E-06	5.50	55000	0.02	161
Other organic materials	Polybutadiene derivative	Proprietary	2.67 E-06	4.50	45000	0.01	131
Other organic materials	Epoxy resin	Proprietary	1.48 E-06	2.50	25000	0.01	73
Other organic materials	Butadiene Copolymer	Proprietary	8.90 E-07	1.50	15000	0.00	44
Others	Additive	Proprietary	8.90 E-07	1.50	15000	0.00	44
Others	Peroxide	Proprietary	2.97 E-07	0.50	5000	0.00	15
Subtotal			5.93 E-05	100.0	1000000	0.29	2922

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.03 E-02**	**100**	**1000000**

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